

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	MDG/23/13703
1.3 Title of PCN	ST Shenzhen (China) TSSOP20 package copper alloy bonding wire introduction on STM32G03x and STM32G04x listed products
1.4 Product Category	STM32G03x STM32G04x
1.5 Issue date	2023-01-22

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	KRISZTINA NEMETH
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Bond wire material, diameter	ST Shenzhen (China)

4. Description of change

	Old	New
4.1 Description	Wire bonding material: - ST Shenzhen (China) Silver alloy wire - Amkor ATP (Philippines) gold wire	Wire bonding material: - ST Shenzhen (China) Copper Alloy wire - Amkor ATP (Philippines) gold wire
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impact on form, Fit, Function	

5. Reason / motivation for change

5.1 Motivation	To improve service
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by ST internal tools
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7. Timing / schedule

7.1 Date of qualification results	2023-03-28
7.2 Intended start of delivery	2023-04-06
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	13703 MDG-GPM-RER2219 PCN13703 PCN13886 STS TSSOP20 Cu alloy wire intro on STM32C0 - reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2023-01-22

9. Attachments (additional documentations)

13703 Public product.pdf
13703 MDG-GPM-RER2219 PCN13703 PCN13886 STS TSSOP20 Cu alloy wire intro on STM32C0 - reliability plan.pdf
13703 PCN13703_Additional information.pdf

10. Affected parts

10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32G030F6P6	
	STM32G030F6P6TR	
	STM32G031F4P6	
	STM32G031F6P6	
	STM32G031F6P7	
	STM32G031F8P3	
	STM32G031F8P6	
	STM32G041F8P6	
	STM32G031F6P7TR	

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